

Prosperity Dielectrics Co., Ltd.

No.566-1, Kaoshi Rd., Yangmei, Taoyuan 32668, Taiwan (R.O.C.)

Tel : 886-3-4753355

Fax : 886-3-4854959

Messrs. : 興鴻宇

Date : 2019/11/13

APPROVAL SHEET

Product Name : High Capacitance Multilayer Ceramic Chip Capacitors

Part No. : FS43X105K101EFG

Description : Size 1812, X7R, 1uF, ±10%, 100V

PREPARED BY	APPROVED BY

信昌電子陶瓷股份有限公司

PROSPERITY DIELECTRICS CO., LTD.

桃園市楊梅區高獅路 566-1 號 <http://www.pdc.com.tw>

Tel : 03-4753355 ext :

Fax : 03-4854959

Contactor : _____ **Mobile :** _____

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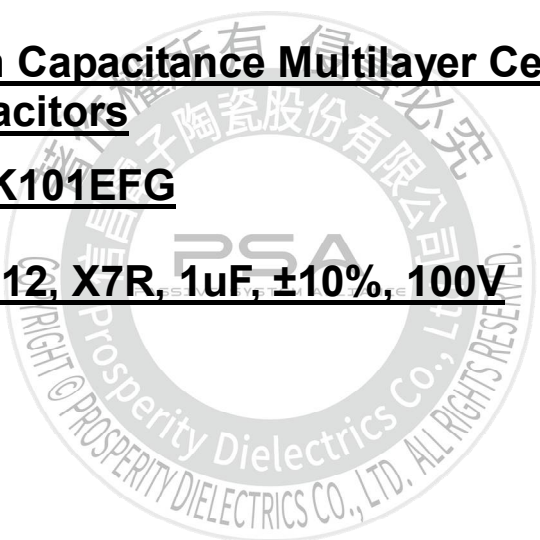
SPECIFICATION

FOR

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SPEC. No. : FS-083-017-01

DATE : 2019/11/13

DRAWN BY	CHECEKED BY	APPROVED BY
<i>Jane Hsiao</i>	<i>Yvens Chou</i>	<i>Joseph Ling</i>

1. INTRODUCTION

PDC FS Series green type capacitors are manufactured by using environmental friendly material without lead or cadmium. These capacitors feature series connection of multi-layer capacitor units in a MLCC to realize high voltage performance. This special design can distribute voltage gradients throughout the entire capacitor, so as to prevent short circuit failure. It is a safety design for LCD back-lighting inverter application.

2. FEATURES

- Realize high capacitance in small sizes.
- Capacitor with lead-free termination (pure Tin).
- RoHS compliant.
- HALOGEN compliant.
- Surface mount suited for wave and reflow soldering.
- High reliability and no polarity.

3. APPLICATIONS

- Digital circuit coupling or decoupling applications.
- For bypassing.
- Ideal for smoothing circuits.
- DC to DC converter.

4. HOW TO ORDER

<u>FS</u>	<u>43</u>	<u>X</u>	<u>105</u>	<u>K</u>	<u>101</u>	<u>E</u>	<u>F</u>	<u>G</u>
PDC Family	Size	Dielectric	Capacitance	Tolerance	Rated Voltage	Packaging	Thickness	Control Code
Table 1	Table 2	Table 3	Table 4	Table 5	Table 6	Table 7	Table 8	Table 9

Table 1	PDC Family
Code	Description
FS	High Capacitance Capacitor $\geq 1\mu\text{F}$ (105)

Table 2	Size					
Code	Description	Code	Description	Code	Description	
03	0201 (0603)	31	1206 (3216)	46	1825 (4563)	
15	0402 (1005)	32	1210 (3225)	52	2211 (5728)	
18	0603 (1608)	42	1808 (4520)	55	2220 (5750)	
21	0805 (2012)	43	1812 (4532)	56	2225 (5763)	

Table 3	Dielectric Material Characteristics			
Code	Description	Code	Description	
N	C0G	X	X7R	
B	X5R	F	Y5V	
S	X6S	A	X7S	

Table 4	Capacitance Rule Code			
Code	Description	Code	Description	
R47	0.47pF	102	$102=10 \times 10^2=1000\text{pF}$	
0R5	0.5pF	104	$104=10 \times 10^4=100\text{nF}$	
100	$100=10 \times 10^0=10\text{pF}$	106	$106=10 \times 10^6=10\mu\text{F}$	

Table 5	Tolerance					
Code	Description	Code	Description	Code	Description	
A	$\pm 0.05 \text{ pF}$	I	-10% ~ 0%	Q	$\pm 0.03 \text{ pF}$	
B	$\pm 0.10 \text{ pF}$	J	$\pm 5 \%$	Z	-20% ~ +80%	
C	$\pm 0.25 \text{ pF}$	K	$\pm 10 \%$	X	+10% ~ +20%	
D	$\pm 0.50 \text{ pF}$	L	0% ~ +10%			
F	$\pm 1 \%$	M	$\pm 20 \%$			
G	$\pm 2 \%$	N	-5% ~ +10%			
H	$\pm 3 \%$	P	$\pm 0.02 \text{ pF}$			

Table 6	Rated Voltage					
Code	Description	Code	Description	Code	Description	
6R3	6.3Vdc	201	200Vdc	152	1500Vdc	
100	10Vdc	251	250Vdc	202	2000Vdc	
160	16Vdc	401	400Vdc	302	3000Vdc	
250	25Vdc	501	500Vdc	402	4000Vdc	
500	50Vdc	631	630Vdc	502	5000Vdc	
101	100Vdc	102	1000Vdc	602	6000Vdc	

Table 7	Packaging Type			
Code	Description	Code	Description	
B	Bulk	T	Tray package	
E	Tape and 7" Reel, Embossed Tape	P	Tape and 7" Reel, Paper Tape	
K	Tape and 10" Reel, Embossed Tape	D	Tape and 10" Reel, Paper Tape	
L	Tape and 13" Reel, Embossed Tape	G	Tape and 13" Reel, Paper Tape	

Table 8	Thickness Description					
Code	Description	Code	Description	Code	Description	
A	0.60 \pm 0.10 mm	I	1.25 \pm 0.20 mm	Q	0.50 +0.02/-0.05 mm	
B	0.8 + 0.15/-0.10 mm	J	1.15 \pm 0.15 mm	R	3.10 \pm 0.30 mm	
C	1.25 \pm 0.10 mm	K	0.50 \pm 0.20 mm	S	0.80 \pm 0.07 mm	
D	1.40 \pm 0.15 mm	L	0.30 \pm 0.03 mm	T	0.85 \pm 0.10 mm	
E	1.60 \pm 0.20 mm	M	0.95 \pm 0.10 mm	U	0.50 \pm 0.10 mm	
F	2.00 \pm 0.20 mm	N	0.50 \pm 0.05 mm	V	0.20 \pm 0.02 mm	
G	2.50 \pm 0.30 mm	O	3.50 \pm 0.20 mm	X	0.80 \pm 0.10 mm	
H	2.80 \pm 0.30 mm	P	1.60 +0.3/-0.10 mm	Z	0.25 \pm 0.03 mm	

Table 9	Special Control Code	
Code	Description	
G	RoHS Compliant	
O	Gold plating (Size \geq 0603)	

5. EXTERNAL DIMENSIONS

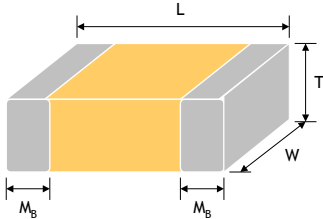
Size Inch (mm)	L (mm)	W (mm)	Code / T (mm)	M _B (mm)	
0201(0603)	0.60±0.03 0.60±0.05 (Cap.≥0.68μF) 0.60±0.09 (Cap.≥1.0μF)	0.30±0.03 0.30±0.05 (Cap.≥0.68μF) 0.30±0.09 (Cap.≥1.0μF)	See No.4 Reference Table 8	0.15±0.05	
0402(1005)	1.00±0.10 1.00±0.20 ^{#1}	0.50±0.10 0.50±0.20 ^{#1}		0.25 +0.05/-0.10	
0603(1608)	1.60±0.15 1.60±0.20 ^{#2}	0.80±0.15 0.80±0.20 ^{#2}		0.40±0.15	
0805(2012)	2.00±0.20	1.25±0.20		0.50±0.20	
1206(3216)	3.20±0.20 3.20 +0.30/-0.10 ^{#3}	1.60±0.20 1.60 +0.30/-0.10 ^{#3}		0.60±0.20	
1210(3225)	3.20±0.30	2.50±0.30		0.75±0.35	
1812(4532)	4.50±0.40	3.20±0.30		0.75±0.35	
1825(4563)	4.50±0.40	6.30±0.40		0.75±0.35	
2220(5750)	5.70±0.40	5.00±0.40		0.85±0.35	
2225(5763)	5.70±0.40	6.30±0.40		0.85±0.35	

Fig. 5.1 The outline of MLCC

^{#1} For 0402 size K thickness products. ^{#2} For 0603/Cap.≥10μF or 0603(≤6.3V)/Cap.≥4.7μF or 0603(>10V)/Cap.>1μF products. ^{#3} For 1206 size P thickness products.

6. GENERAL ELECTRICAL DATA

Dielectric	X7R	X7S	X6S	X5R	Y5V
Size	0402, 0603, 0805, 1206, 1210, 1812, 1825, 2220, 2225	0402, 0603, 0805, 1206, 1210	0201, 0402, 0603, 0805, 1206, 1210	0201, 0402, 0603, 0805, 1206, 1210	0402, 0603, 0805, 1206, 1210, 1812
Rated voltage (WVDC)	6.3V, 10V, 16V, 25V, 50V, 100V, 250V, 500V, 630V	6.3V, 10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V, 35V, 50V	4V, 6.3V, 10V, 16V, 25V, 35V, 50V	6.3V, 10V, 16V, 25V, 35V, 50V, 100V
Capacitance range*	1μF to 47μF	1μF to 100μF	1μF to 100μF	1μF to 220μF	1μF to 100μF
Capacitance tolerance**	K(±10%), M(±20%)	K(±10%), M(±20%)	K(±10%), M(±20%)	K(±10%), M(±20%)	Z(-20/+80%)
Tan δ*	Note 1				
Operating temperature	-55 to +125°C	-55 to +125°C	-55 to +105°C	-55 to +85°C	-25 to +85°C
Capacitance characteristic	±15%	±22%	±22%	±15%	+30/-80%
Termination	Cu or Ag/Ni/Sn or Au (lead-free termination)				

* Measured at the condition of 30~70% related humidity.

X7R/X7S/X6S/X5R : Apply 1.0±0.2Vrms, 1.0KHz±10% for Cap.≤10μF; 0.5±0.2Vrms, 120Hz±20% for Cap.>10μF, at 25°C ambient temperature.

Y5V : Apply 1.0±0.2Vrms, 1.0KHz±10% for Cap.≤10μF; 0.5±0.2Vrms, 120Hz±20% for Cap.>10μF, at 20°C ambient temperature.

** Preconditioning for Class II MLCC : Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.

Note 1 : X7R/X7S/X6S/X5R

Rated	D.F.≤	Exception of D.F.≤
≥100V	≤2.5%	≤3.5% 0603≥0.047μF, 0805=0.1μF, 1206≥0.47μF, 1812≥4.7μF, 1825≥4.7μF, 2220≥4.7μF, 2225≥4.7μF
		≤5% 0603≥0.068μF, 0805>0.1μF, 1206>1μF, 1210≥2.2μF
		≤10% 0805>0.22μF, 1210≥3.3μF
50V	≤2.5%	≤3.5% 0201(50V), 0603≥0.047μF, 0805≥0.1μF, 1206≥0.47μF, 1210≥2.2μF, 1812≥4.7μF, 1825≥4.7μF, 2220≥4.7μF, 2225≥4.7μF
		≤5% 0201≥0.01μF, 1210≥4.7μF
		≤10% 0402≥0.012μF, 0603>0.1μF, 0805≥1μF, 1206≥2.2μF, 1210≥10μF
35V	≤3.5%	≤10% 0603≥1μF, 0805≥2.2μF, 1206≥2.2μF, 1210≥10μF
		≤5% 0201≥0.01μF, 0805≥1μF, 1210≥10μF
		≤7% 0603≥0.33μF, 1206≥4.7μF
25V	≤3.5%	≤10% 0201≥0.1μF, 0402≥0.10μF, 0603≥0.47μF, 0805≥2.2μF, 1206≥6.8μF, 1210≥22μF
		≤12.5% 0402≥0.47μF
		≤5% 0201≥0.01μF, 0402≥0.033μF, 0603≥0.15μF, 0805≥0.68μF, 1206≥2.2μF, 1210≥4.7μF
16V	≤3.5%	≤10% 0201≥0.1μF(0201/X7R≥0.022μF), 0402≥0.22μF, 0603≥0.68μF, 0805≥2.2μF, 1206≥4.7μF, 1210≥22μF
		≤15% 0201≥0.012μF, 0402≥0.33μF(0402/X7R≥0.22μF), 0603≥0.33μF, 0805≥2.2μF, 1206≥2.2μF, 1210≥22μF
10V	≤5%	≤10% 0201≥0.012μF, 0402≥0.33μF(0402/X7R≥0.22μF), 0603≥0.33μF, 0805≥2.2μF, 1206≥2.2μF, 1210≥22μF
		≤15% 0201≥0.1μF, 0402≥1μF
6.3V	≤10%	≤15% 0201≥0.1μF, 0402≥1μF, 0603≥10μF, 0805≥4.7μF, 1206≥47μF, 1210≥100μF
		≤20% 0402≥2.2μF
4V	≤15%	---

Y5V

Rated	D.F.≤	Exception of D.F.≤
≥50V	≤5%	≤7% 0603≥0.1μF, 0805≥0.47μF, 1206≥4.7μF
		≤12.5% 1210≥6.8μF
35V	≤7%	---
25V	≤5%	≤7% 0402≥0.047μF, 0603≥0.1μF, 0805≥0.33μF, 1206≥1μF, 1210≥4.7μF
		≤9% 0402≥0.068μF, 0603≥0.47μF, 1206≥4.7μF, 1210≥22μF
16V (C<1.0μF)	≤7%	≤9% 0402≥0.068μF, 0603≥0.68μF
		≤12.5% 0402≥0.22μF
16V (C≥1.0μF)	≤9%	≤12.5% 0603≥2.2μF, 0805≥3.3μF, 1206≥10μF, 1210≥22μF, 1812≥47μF
		≤20% 0402≥0.47μF
10V	≤12.5%	---
6.3V	≤20%	---

7. PACKAGE DIMENSION AND QUANTITY

Size	Thickness (mm)	Paper tape		Plastic tape	
		7" reel	13" reel	7" reel	13" reel
0201(0603)	0.30±0.03	15k	70k	-	-
	0.30±0.05	15k	-	-	-
	0.30±0.09	15k	-	-	-
0402(1005)	0.50±0.05	10k	50k	-	-
	0.50 +0.02/-0.05	10k	50k	-	-
	0.50±0.20	10k	-	-	-
0603(1608)	0.50±0.10	4k	-	-	-
	0.80±0.07	4k	15k	-	-
	0.80 +0.15/-0.10	4k	15k	-	-
0805(2012)	0.50±0.10	4k	15k	-	-
	0.60±0.10	4k	15k	-	-
	0.80±0.10	4k	15k	-	-
	0.85±0.10	4k	15k	-	-
	1.25±0.10	-	-	3k	10k
1206(3216)	0.80±0.10	4k	15k	-	-
	0.85±0.10	4k	15k	-	-
	0.95±0.10	-	-	3k	10k
	1.15±0.15	-	-	3k	10k
	1.25±0.10	-	-	3k	10k
	1.60±0.20	-	-	2k	10k
	1.60 +0.30/-0.10	-	-	2k	9k
1210(3225)	0.85±0.10	-	-	3k	10k
	0.95±0.10	-	-	3k	10k
	1.25±0.10	-	-	3k	10k
	1.60±0.20	-	-	2k	-
	2.00±0.20	-	-	1k	6k
1808(4520)	2.50±0.30	-	-	1k	6k
	1.25±0.10	-	-	2k	10k
	1.60±0.20	-	-	2k	8k
1812(4532)	2.00±0.20	-	-	1k	6k
	1.25±0.10	-	-	1k	5k
	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
1825(4563)	2.50±0.30	-	-	0.5k	3k
	2.80±0.30	-	-	0.5k	-
	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
2220(5750)	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-
	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
2225(5763)	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-
	1.60±0.20	-	-	1k	-

Unit : pcs

7. PACKAGE DIMENSION AND QUANTITY

7.1. EMBOSSED TAPE DIMENSIONS

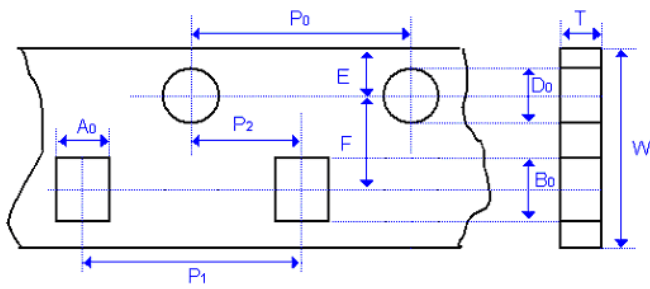


Fig. 7.1 The dimension of paper tape

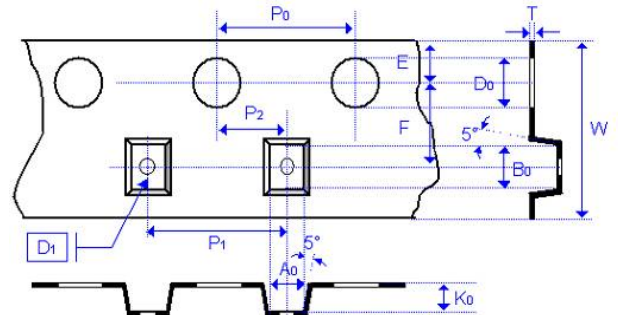


Fig. 7.2 The dimension of plastic tape

Size	0201	0402	0603		0805	
Chip Thickness	0.30±0.03	0.50±0.05 0.50±0.10	0.80±0.07	0.80 +0.15/-0.1	0.80±0.10	1.25±0.10 1.25±0.20
A ₀	0.39±0.07	0.70±0.20	1.00 +0.05/-0.1	1.02 +0.05/-0.1	1.50±0.10	<1.65
B ₀	0.69±0.07	1.20±0.20	1.80±0.10	1.80±0.10	2.30±0.10	<2.40
T	≤0.50	≤0.80	0.95±0.05	0.97±0.05	0.95±0.05	0.23±0.05
K ₀	-	-	-	-	-	<2.50
W	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.00±0.10	40.00±0.10	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P ₁	2.00±0.05	2.00±0.05	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.50 +0.10/-0
D ₁	-	-	-	-	-	1.00±0.10
E	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05
Unit :	mm	mm	mm	mm	mm	mm

Size	1206			1210		1812	
Chip Thickness	0.80±0.10	0.95±0.10 1.25±0.10	1.60±0.20 1.60+0.3/-0/1	0.95±0.10 1.25±0.10 1.60±0.20	2.50±0.30	1.25±0.10 1.60±0.20 2.00±0.20	2.50±0.30
A ₀	2.00±0.10	<2.00	<2.00	<3.05	<3.10	<3.90	<3.90
B ₀	3.50±0.10	<3.60	<3.70	<3.80	<4.00	<5.30	<5.30
T	0.95±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.25±0.05	0.25±0.05
K ₀	-	<2.50	<2.50	<2.50	<3.50	<2.50	<3.00
W	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	12.00±0.20	12.00±0.20
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P ₁	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	8.00±0.10	8.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.55±0.05	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0
D ₁	-	1.00±0.10	1.00±0.10	1.00±0.10	1.00±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	5.50±0.05	5.50±0.05
Unit :	mm	mm	mm	mm	mm	mm	mm

7. PACKAGE DIMENSION AND QUANTITY

Size	1825		2220		2225	
Chip Thickness	1.60±0.20 2.00±0.20	2.50±0.30	1.40±0.15 1.60±0.20 2.00±0.20	2.50±0.30	1.60±0.20 2.00±0.20	2.50±0.30
A ₀	<6.80	<6.80	<5.80	<5.80	<6.80	<6.80
B ₀	<5.30	<5.30	<6.50	<6.50	<6.50	<6.50
T	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10
K ₀	<2.50	<3.10	<2.50	<3.10	<2.50	<3.10
W	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P ₁	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0
D ₁	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05
Unit :	mm	mm	mm	mm	mm	mm

7.2. REEL DIMENSIONS

Size	0201, 0402, 0603, 0805, 1206, 1210			1808, 1812, 1825, 2220, 2225
Reel size	7"	7"	13"	7"
C	13.0 +0.5/-0.2	13.0 +0.5/-0.2	13.0 +0.7/-0.3	13.0 +0.5/-0.2
W ₁	8.4 +1.5/-0	12.4 +2.0/-0	8.4 +2.0/-0	12.4 +2.0/-0
A	178.0 ±0.10	178.0 ±0.10	330.0 ±1.0	178.0 ±0.10
N	60.0 +1.0/-0	80.0 ±1.0	100 ±1.0	60.0 +1.0/-0

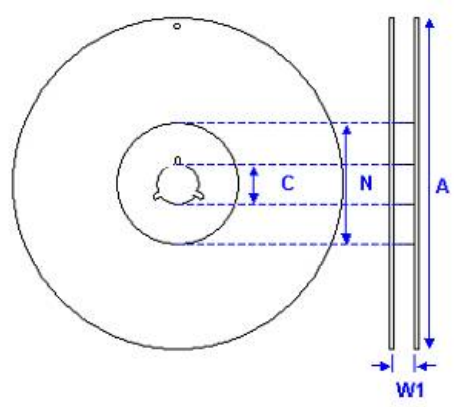


Fig. 7.3 The dimension of reel

8. APPLICATION NOTES

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :
 Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 12 months after shipment and checked the solderability before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

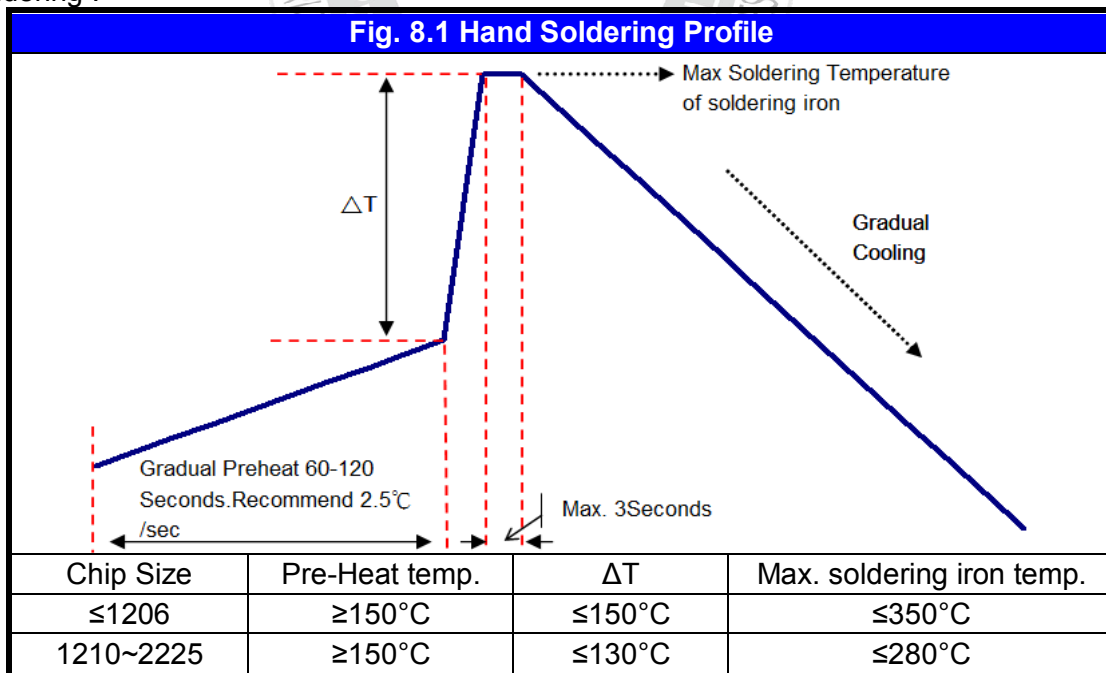
PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required. The rate of preheat should not exceed 3°C per second.

SOLDERING

Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

a.) Hand soldering :



* Soldering iron tip diameter ≤ 1.0 mm and wattage max. 20W.

* The Capacitors shall be pre-heated and that the temperature gradient between the devices and the tip of the soldering iron.

* The required amount of solder shall be melted on the soldering tip.

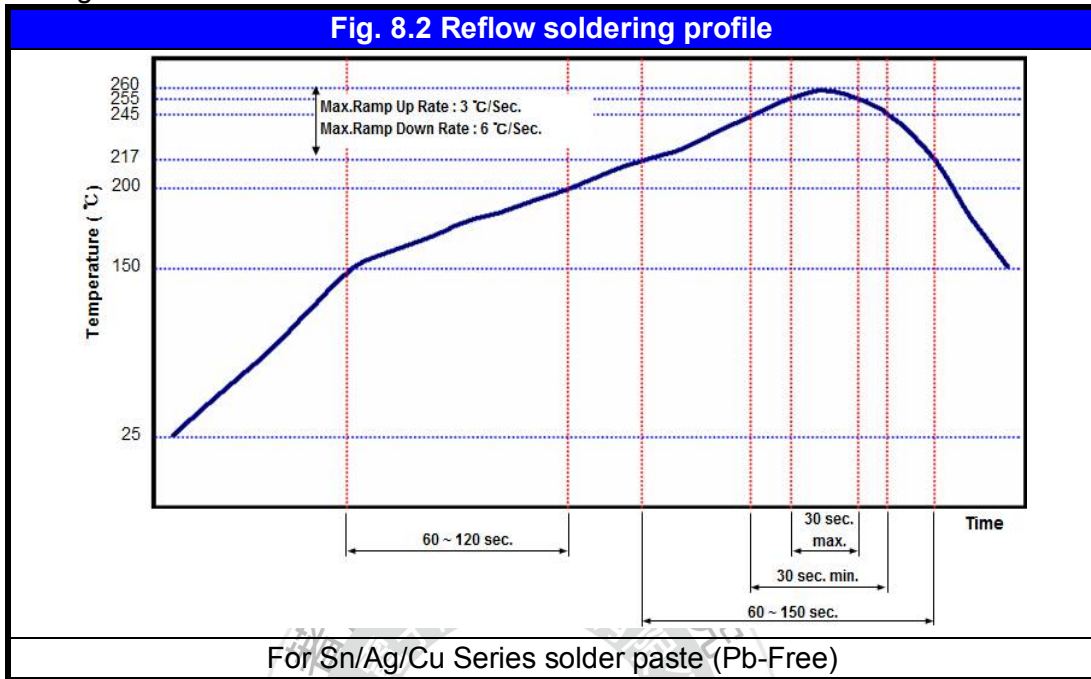
* The tip of iron should not contact the ceramic body directly.

* The Capacitors shall be cooled gradually at room temperature after soldering.

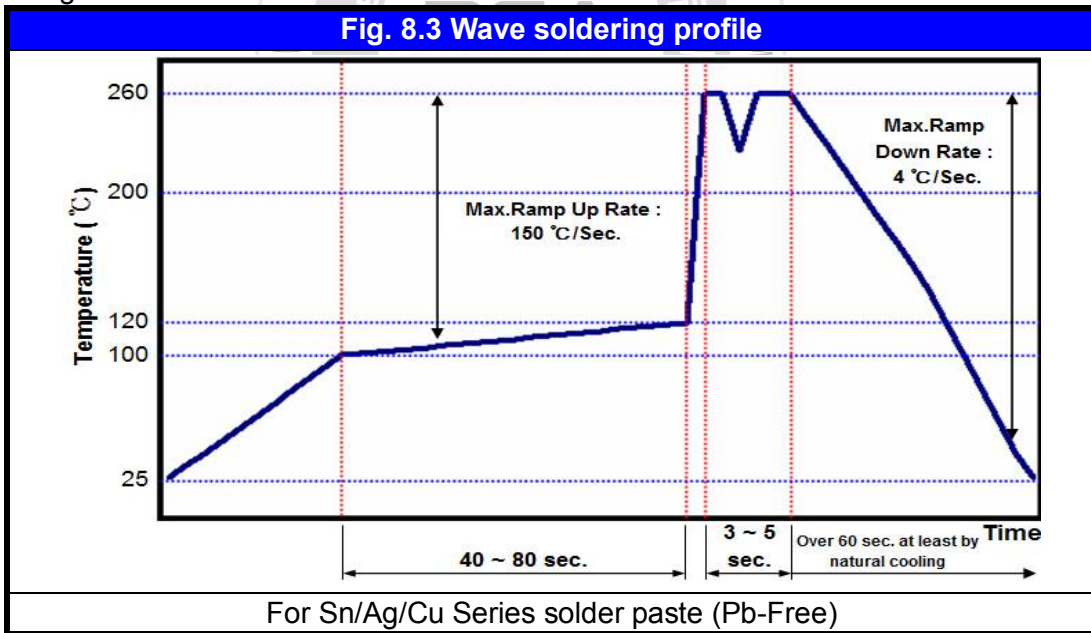
* Forced air cooling is not allowed.

8. APPLICATION NOTES

b.) Reflow soldering :



c.) Wave soldering :



Soldering conditions :

Class I :

Size Inch (mm)	Temper. Cher.	Capacitance	Condition	
			Wave	Reflow
≤0402 (1005)	All Class I	All	X	O
0603 (1608)	All Class I	All	O	O
0805 (2012)	All Class I	All	O	O
1206 (3216)	All Class I	All	O	O
≥1210 (3225)	All Class I	All	X	O

8. APPLICATION NOTES

Soldering conditions :
 Class II :

Size Inch (mm)	Temper. Cher.	Capacitance	Condition	
			Wave	Reflow
≤0402 (1005)	All Class II	All	X	O
0603 (1608)	All Class II	Cap. <2.2μF	O	O
		Cap. ≥2.2μF	X	O
0805 (2012)	All Class II	Cap. <4.7μF	O	O
		Cap. ≥4.7μF	X	O
1206 (3216)	All Class II	Cap. <4.7μF	O	O
		Cap. ≥4.7μF	X	O
≥1210 (3225)	All Class II	All	X	O

Soldering height :

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.
 (Reference from IPC-610E)

The diagram illustrates a cross-section of a chip on a substrate. The chip is shown in yellow and grey. A vertical double-headed arrow indicates the 'Chip Thickness'. A horizontal double-headed arrow at the bottom indicates the 'Soldering Height', which is the height of the solder joint between the chip and the substrate.

COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.